

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	6	("5589226" "5681757" "6541063").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:33
S2	2360902	gluing glued glue bonding bonded bond	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:35
S3	536268	S2 with (glue adhesive sealant binder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:35
S4	77078	S3 and (circuit and component)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:35
S5	7123	S3 same (circuit and component)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:36
S6	2283	S3 with (circuit and component)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:36
S7	858	S6 and air	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:36

S8	259	S7 and array	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:36
S9	2276366	adhesive glue binder paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/27 12:58
S10	38446	S9 near5 pattern	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/27 12:58
S11	7227924	laminating lamination laminate laminated bonded bond bonding attaching attached attach glued gluing glue pasting pasted paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:59
S12	53672	S11 with (circuit and component)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 12:59
S13	2101	S12 and S10	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 13:00
S14	220	S13 and dot	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 13:00
S15	21548	(dispensing dispensed dispense) near5 (adhesive glue binder paste)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 13:02

S16	1567	S12 and S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 13:02
S17	366	S16 and bubble	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 13:02
S18	1626	S10 and S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 13:10
S19	187	S18 and bubble	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/27 13:11
S20	15701	((156/295.ccls.) or (156/87.ccls.) or (29/832.ccls.) or (29/840.ccls.) or (29/25.01.ccls.) or (438/118.ccls.) or (438/119.ccls.) or (257/E21.514.ccls.) or (257/E21.505. ccls.)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 10:37
S21	2462405	adhesive glue paste binder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:38
S22	3954658	dot spot array pattern	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:39
S23	110861	S21 with S22	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:39

S24	1805	S20 and S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:39
S25	5519664	circuit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:39
S26	1441	S24 and S25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:39
S27	8284892	laminating joining joined join lamination laminate laminated adhering adhered adhere attaching attached attach gluing glued glue pasting pasted pasted bonding bond bonded	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:41
S28	1390	S26 and S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:41
S29	72236	S25 same S27 same S21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:42
S30	12103	S29 and S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:42
S31	7391	S29 same S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:42

S32	880	S30 and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:42
S33	447	S31 and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/28 10:42
S34	91	("3683212" "5053100" "5092864" "5187123" "5227813" "5235352" "5400064" "5415679" "5423889" "5426455" "5435060" "5436648" "5444467").PN. OR ("5681757").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/28 10:51
S35	40	("2264632" "3963551" "4239576" "4255644" "4480983" "4515297" "4545840" "4577398" "4709849" "4803124").PN. OR ("5187123").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/28 10:53
S36	34	("2794417" "3077857" "3570721" "3970222" "4030640" "4154379" "4156398" "4156495" "4295596").PN. OR ("4515297").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/28 10:54

S37	52	("2264632" "2533704" "2575976" "3963551" "4239576" "4255644" "4480983" "4515297" "4545840" "4577398" "4709849").PN. OR ("4803124").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/28 10:56
S38	31	("4515297" "4803124" "4874444" "4938383" "4989796" "5187123").PN. OR ("5423889").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/28 10:58
S39	75764	lead adj frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:09
S40	531803	circuit adj board	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:09
S41	594127	S39 or S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:09
S42	125095	S41 with S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:09
S43	16666	S42 with S21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:10

S44	111060	S31 saem S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:10
S45	7391	S31 same S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:10
S46	447	S45 and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:10
S47	5690421	multiple multiplicity plural plurality	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:11
S48	35573	S47 near5 S21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:11
S49	1023	S48 same S41	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:11
S50	671	S49 same S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:11
S51	6	("5589226" "5681757" "6541063").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:24

S52	2	"2002143416"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:40
S53	0	"2002143416 A1"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:40
S54	0	"02143416 A1"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:40
S55	0	"02143416A1"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:40
S56	1	"02143416A"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:40
S57	320	seshan.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:41
S58	11	"6129040"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/28 11:43

S59	67	("3337941" "4144449" "4346293" "4351264" "4378134" "4383359" "4584047" "4610083" "4615093" "4819326" "4868007" "4915770" "4934891" "4937511" "5023544" "5024720" "5086559" "5150423" "5157617" "5157734" "5191693" "5195234" "5213653" "5248362" "5249239" "5275657" "5278634" "5289625" "5309223" "5311304" "5342460" "5380099" "5400497" "5415693" "5455409" "5459794" "5475919" "5488771" "5499756" "5515600" "5547537" "5553376" "5559727" "5562384" "5564188" "5592562" "5650081" "5669970" "5694443" "5708419" "5713125" "5715594" "5735040" "5788379" "5829689"	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/28 11:44
-----	----	--	---------------------------	----	-----	---------------------

"5838754"					
"5885052"					
"5941674"					
"Re34615").PN. OR					
("6129040").URPN.					

10/ 29/ 2009 3:00:05 PM

**C:\ Documents and Settings\ jlee12\ My Documents\ EAST\ Workspaces\ 10597232 method for
gluing a circuit component to a circuit board.wsp**